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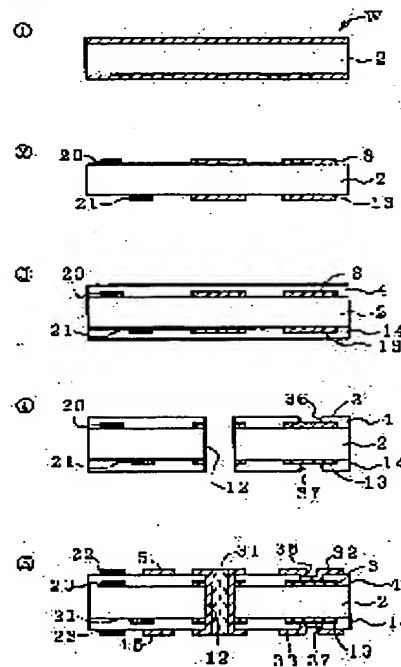
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(54) MANUFACTURING METHOD FOR PRINTED WIRING BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a method for manufacturing a printed wiring board that can cope with the densification and miniaturization of a wiring pattern.

SOLUTION: Related to the method for manufacturing the printed wiring board, core wiring pattern layers 3 and 13 and positioning alignment marks 20 and 21 are formed on both principal surfaces of a core material 2 mainly containing an insulating resin. The alignment marks 20 and 21 and the core wiring pattern layers 3 and 13 are coated with first buildup layers 4 and 14 comprising insulating resins. The alignment marks 20 and 21 are detected by a CCD sensor through the buildup layers 4 and 14. Based on the result of the detection, a through hole 12 penetrating the core material 2, the core wiring pattern layers 3 and 13 and the first buildup layers 4 and 14 is formed by using a laser beam.



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